



materials



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Advanced Flexible Materials for Printed Electronics

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Message from the Guest Editor

Printed Electronics is one of the fastest growing fields. Currently, a huge research effort is being undertaken to allow smart devices to be printed onto flexible, bendable, and even stretchable substrates.

To further this area of research, investigation in three important aspects of Printed Electronics is required: ink formulation, printing technology and interaction of the inks with the substrates. Printing on flexible substrates such as foils, paper, textiles, and other fiber-based substrates requires proper understanding of the interaction between the ink formulation and these substrates. Both the flow behaviour and wetting on the substrate of choice and the absorption into the substrate need to be addressed. Further, most of these flexible and stretchable carriers are heat-sensitive, and thus both printing technology and post-processing should be adapted to achieve functional designs.

This Special Issue aims to publish a collection of the latest research on the use of advanced functional materials for ink formulation, the deposition of these new materials with state-of-the-art printing technology, and the understanding of their interactions with a wide variety of substrates.



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Special Issue



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Message from the Editor-in-Chief

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